

IN THE CLAIMS:

Please cancel claims 2-4, 6-7, 9-11, 13-14 without prejudice to or disclaimer of the subject matter recited therein.

Please add claims 18 and 19 and amend claims 1, 5, 8, and 12 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Currently Amended) A planar package structure for a high power light emitting diode, comprising:
a substrate;
a package material;
5 a light emitting diode chip, in direct contact with the substrate and having a main light emitting surface providing a light source; and
a planar optical modulation unit disposed on the package material, the planar optical modulation unit is located above the main light emitting surface and utilized for modulating an optical phase of the light source.

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Claims 2-4 (Canceled)

Claim 5. (Currently Amended) The planar package structure for high power light emitting diode of claim 1, wherein the planar optical modulation unit is configured to perform performs a diffractive optical phase modulation.

Claims 6-7 (Canceled)

Claim 8. (Currently Amended) A planar package structure for a high power light emitting diode, comprising:
a substrate;
a package material;
a plurality of light emitting diode chips in direct contact with the substrate, each light emitting diode chip having a main light emitting surface providing a

light source; and

a plurality of planar optical modulation units disposed on the package material, each of the planar optical modulation units is located above each of the main light emitting surface respectively, and utilized for modulating the optical phase of each of the light sources.

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Claims 9-11 (Canceled)

Claim 12. (Currently Amended) The planar package structure for high power light emitting diode of claim 8, wherein each of the planar optical modulation units is configured to perform performs- a diffractive optical phase modulation.

Claims 13-14 (Canceled)

Claims 15-17 (Cancelled)

Claim 18. (New) The planar package structure for high power light emitting diode of claim 1, wherein substantially all of a surface of the substrate underlying the planar optical modulation unit is substantially parallel to a surface of the planar optical modulation unit.

Claim 19. (New) The planar package structure for high power light emitting diode of claim 8, wherein substantially all of a surface of the substrate underlying the planar optical modulation unit is substantially parallel to a surface of the planar optical modulation unit.